

# PCS3P25811, PCS3P25812, PCS3P25814

## Product Preview Spread Spectrum Clock Generator

### Product Description

The PCS3P25811/12/14 devices are versatile spread spectrum frequency modulators designed specifically for a wide range of input clock frequencies from 4 MHz to 32 MHz.

The PCS3P25811/12/14 reduce electromagnetic interference (EMI) at the clock source, allowing system wide reduction of EMI of down stream clock and data dependent signals. It allows significant system cost savings by reducing the number of circuit board layers, ferrite beads, shielding, and other passive components that are traditionally required to pass EMI regulations.

The PCS3P25811/12/14 can generate an EMI reduced clock from crystal, ceramic resonator, or system clock.

The PCS3P25811/12/14 modulate the output of a single PLL in order to “spread” the bandwidth of a synthesized clock, and more importantly, decreases the peak amplitudes of its harmonics. This results in significantly lower system EMI compared to the typical narrow band signal produced by oscillators and most frequency generators. Lowering EMI by increasing a signal’s bandwidth is called ‘spread spectrum clock generation’.

The PCS3P25811/12/14 use the most efficient and optimized modulation profile approved by the FCC and is implemented in a proprietary all-digital method.

The PCS3P25811/12/14 have 2 pins S0 and S1 to control the selection of Center Spread, Down Spread and No-Spread functions. Additionally there is a 3 level logic control FSEL, for selecting one of the three different frequency ranges within the operating frequency range. Refer *Input/Output Frequency Range Selection Table*.

The PCS3P25811/12/14 operate from a 2.8 V to 3.6 V supply and are available in 8 pin SOIC, and 8L 2 mm x 2 mm WDFN packages.

This document contains information on a product under development. ON Semiconductor reserves the right to change or discontinue this product without notice.

### Applications

The PCS3P25811/12/14 are targeted towards EMI management in applications such as LCD Panels, MFPs, Digital copiers, Networking, PC peripheral devices, consumer electronics, and embedded controller systems.

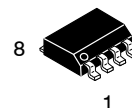
### Features

- Generates a 1x (PCS3P25811), 2x (PCS3P25812) and 4x (PCS3P25814) Low EMI Spread Spectrum Clock of the Input Frequency
- Provides up to 15 dB of EMI Suppression
- Input Frequency: 4 MHz – 32 MHz
- Output Frequency: PCS3P25811: 4 MHz – 32 MHz  
PCS3P25812: 8 MHz – 64 MHz  
PCS3P25814: 16 MHz – 128 MHz

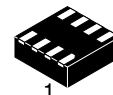


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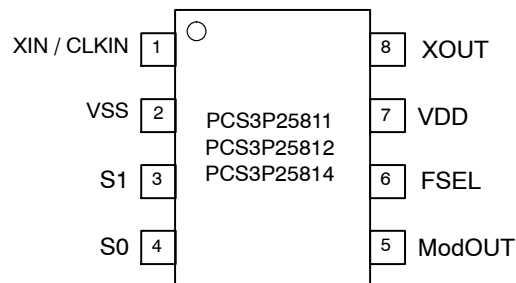


SOIC8-NB EP  
CASE 751BU



WDFN8 2x2, 0.5P  
CASE 511AQ

### PIN CONFIGURATION



### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 9 of this data sheet.

- Selectable Spread Options: Down Spread and Center Spread
- Low Power Dissipation: 3.3 V: 20 mW (typ) @ 6 MHz  
3.3 V: 24 mW (typ) @ 12 MHz  
3.3 V: 30 mW (typ) @ 24 MHz
- Low Inherent Cycle-to-Cycle Jitter
- Supply Voltage: 2.8 V to 3.6 V
- LVC MOS Input and Output
- Functional and Pinout Compatible to Cypress CY25811, CY25812 and CY25814
- 8-pin SOIC, and 8L 2 mm x 2 mm WDFN (TDFN) Packages
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

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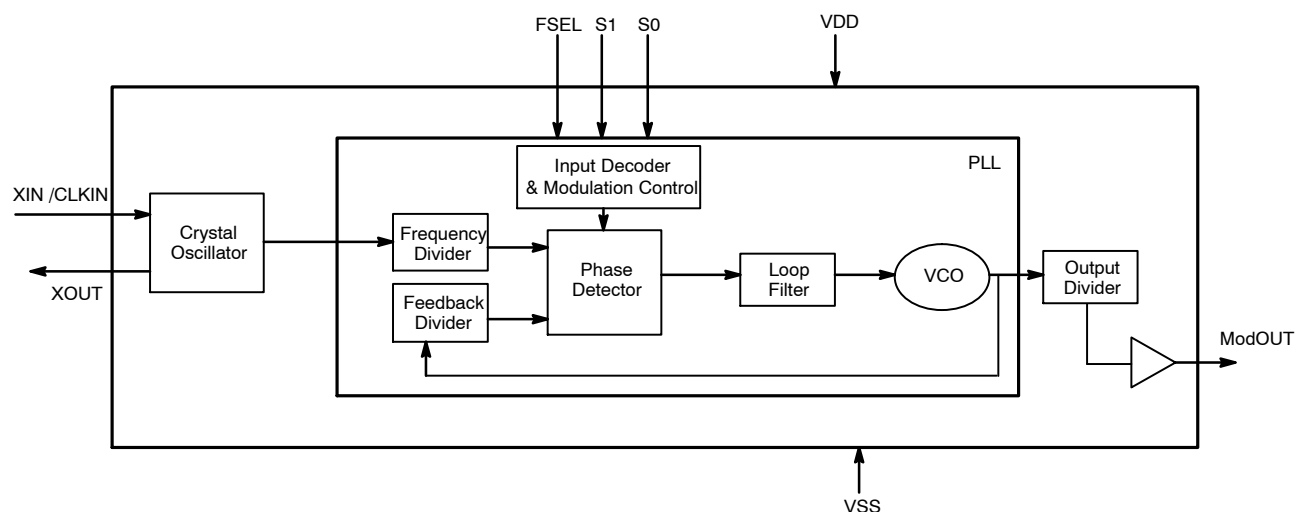


Figure 1. Block Diagram

Table 1. PIN DESCRIPTION

Pin #	Pin Name	Type	Description
1	XIN / CLKIN	Input	Crystal connection or External Clock input.
2	VSS	Power	Ground to entire chip.
3	S1	Input	Digital 3 level logic input (1–M–0) used to select Center, Down and No spread options. (Refer to <i>Frequency Deviation Selection Table</i> ). Default = M.
4	S0	Input	Digital 3 level logic input (1–M–0) used to select Center, Down and No spread options. (Refer to <i>Frequency Deviation Selection Table</i> ). Default = M.
5	ModOUT	Output	Spread Spectrum Clock Output.
6	FSEL	Input	Frequency range select. Digital 3 level logic input (1–M–0) used to select Input Clock frequency range (Refer to <i>Input/Output Frequency Range Selection Table</i> ). Default = M.
7	VDD	Power	Power supply for the entire chip (2.8 V to 3.6 V).
8	XOUT	Output	Crystal connection. If using an external reference, this pin must be left unconnected.

Table 2. OUTPUT FREQUENCY RANGE SELECTION

FSEL (pin 6)	Part Number						Modulation Rate
	PCS3P25811 (1x)		PCS3P25812 (2x)		PCS3P25814 (4x)		
	Input (MHz)	Output (MHz)	Input (MHz)	Output (MHz)	Input (MHz)	Output (MHz)	
0	4 – 8	4 – 8	4 – 8	8 – 16	4 – 8	16 – 32	Input Frequency / 128
1	8 – 16	8 – 16	8 – 16	16 – 32	8 – 16	32 – 64	Input Frequency / 256
M	16 – 32	16 – 32	16 – 32	32 – 64	16 – 32	64 – 128	Input Frequency / 512

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**Table 3. OUTPUT FREQUENCY DEVIATION SELECTION**

CLKIN (MHz)	FSEL	S1 = 0 S0 = 0	S1 = 0 S0 = M	S1 = 0 S0 = 1	S1 = M S0 = 0	S1 = 1 S0 = 1	S1 = 1 S0 = 0	S1 = M S0 = 1	S1 = 1 S0 = M	S1 = M S0 = M
		Center	Center	Center	Center	Down	Down	Down	Down	No Spread
4 – 5	0	±1.4	±1.2	±0.6	±0.5	–3	–2.2	–1.9	–0.7	0
5 – 6	0	±1.3	±1.1	±0.5	±0.4	–2.7	–1.9	–1.7	–0.6	0
6 – 7	0	±1.2	±0.9	±0.5	±0.4	–2.5	–1.8	–1.5	–0.6	0
7 – 8	0	±1.1	±0.9	±0.4	±0.3	–2.3	–1.7	–1.4	–0.5	0
8 – 10	1	±1.4	±1.2	±0.6	±0.5	–3	–2.2	–1.9	–0.7	0
10 – 12	1	±1.3	±1.1	±0.5	±0.4	–2.7	–1.9	–1.7	–0.6	0
12 – 14	1	±1.2	±0.9	±0.5	±0.4	–2.5	–1.8	–1.5	–0.6	0
14 – 16	1	±1.1	±0.9	±0.4	±0.3	–2.3	–1.7	–1.4	–0.5	0
16 – 20	M	±1.4	±1.2	±0.6	±0.5	–3	–2.2	–1.9	–0.7	0
20 – 24	M	±1.3	±1.1	±0.5	±0.4	–2.7	–1.9	–1.7	–0.6	0
24 – 28	M	±1.2	±0.9	±0.5	±0.4	–2.5	–1.8	–1.5	–0.6	0
28 – 32	M	±1.1	±0.9	±0.4	±0.3	–2.3	–1.7	–1.4	–0.5	0

NOTE: Frequency Deviation given in the table is for the Input Frequency Range covering PCS3P25811 /12 /14.

## 3 Level Digital Logic

S0, S1, and FSEL digital inputs are designed to sense 3 different logic levels designated as High “1”, Low “0” and Middle “M”. With this 3–Level digital input logic 9 different logic states can be detected.

S0, S1 and FSEL pins include an on chip 100 K (50 K / 50 K) resistor divider. No external application resistors are needed to implement the 3–Level logic levels as shown in table on the right:

Logic	Control Pins	
1	FSEL, S0, S1 to VDD	
M	FSEL, S0, S1 UNCONNECTED	
0	FSEL, S0, S1 to VSS	

**Table 4. OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit
V <sub>DD</sub> , V <sub>IN</sub>	Voltage on any pin with respect to VSS	2.8	3.6	V
T <sub>A</sub>	Operating temperature	0	+70	°C
C <sub>L</sub>	Load Capacitance		15	pF
C <sub>IN</sub>	Input Capacitance		7	pF

**Table 5. ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Rating	Unit
V <sub>DD</sub> , V <sub>IN</sub>	Voltage on any pin with respect to Ground	–0.5 to +4.6	V
T <sub>STG</sub>	Storage temperature	–65 to +125	°C
T <sub>s</sub>	Max. Soldering Temperature (10 sec)	260	°C
T <sub>J</sub>	Junction Temperature	150	°C
T <sub>DV</sub>	Static Discharge Voltage (As per JEDEC STD 22– A114–B)	2	KV

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

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**Table 6. DC ELECTRICAL CHARACTERISTICS**

Symbol	Parameter			Min	Typ	Max	Units
VDD	Supply Voltage			2.8	3.3	3.6	V
V <sub>IL</sub>	Input low voltage (S0, S1, FSEL Inputs)	Commercial Temperature	0		0.15 V <sub>DD</sub>	V	
		Industrial Temperature	0		0.13 V <sub>DD</sub>		
V <sub>IM</sub>	Input middle voltage (S0, S1, FSEL Inputs)			0.4 VDD		0.60 V <sub>DD</sub>	V
V <sub>IH</sub>	Input high voltage (S0, S1, FSEL Inputs)			0.85 VDD		V <sub>DD</sub>	V
V <sub>OL</sub>	Output low voltage (ModOUT Output)	I <sub>OL</sub> = 4 mA			0.4	V	
		I <sub>OL</sub> = 10 mA			1.2		
V <sub>OH</sub>	Output high voltage (ModOUT Output)	I <sub>OH</sub> = −4 mA	2.4			V	
		I <sub>OH</sub> = −6 mA	2				
C <sub>IN</sub>	Input Capacitance (XIN and XOUT)			6		9	pF
I <sub>DD</sub>	Dynamic supply current (Unloaded Output)	Commercial Temperature	XIN / CLKIN = 12 MHz			8	mA
			XIN / CLKIN = 24 MHz			10	
			XIN / CLKIN = 32 MHz			13	
		Industrial Temperature	XIN / CLKIN = 12 MHz			10	mA
			XIN / CLKIN = 24 MHz			12	
			XIN / CLKIN = 32 MHz			15	
I <sub>CC</sub>	Static supply current (XIN / CLKIN pulled to VSS)					0.5	mA

NOTE: The voltage on any input or I/O pin cannot exceed the power pin during power up. All parameters are specified at Commercial and Industrial temperature unless stated otherwise.

**Table 7. AC ELECTRICAL CHARACTERISTICS**

Symbol	Parameter		Min	Typ	Max	Units
f <sub>IN</sub>	Input Clock frequency for PCS3P25811/12/14		4		32	MHz
f <sub>OUT</sub>	ModOUT Clock frequency for PCS3P25811		4		32	MHz
	ModOUT Clock frequency for PCS3P25812		8		64	
	ModOUT Clock frequency for PCS3P25814		16		128	
t <sub>LH</sub> (Notes 1, 2)	ModOUT Rise time (Measured from 20% to 80%)	PCS3P25811/12/14	2		5	nS
		PCS3P25814 when FSEL = M	1		2.2	
t <sub>HL</sub> (Notes 1, 2)	ModOUT Fall time (Measured from 80% to 20%)	PCS3P25811/12/14	2		4.4	nS
		PCS3P25814 when FSEL = M	1		2.2	
T <sub>DCIN</sub>	Input Clock Duty Cycle (XIN / CLKIN)		40		60	%
T <sub>DCOUT</sub> (Notes 1, 2)	Output Clock Duty Cycle (ModOUT)		40		60	%

- Parameters are specified with 15 pF loaded outputs.
- Parameter is guaranteed by design and characterization. Not 100% tested in production.

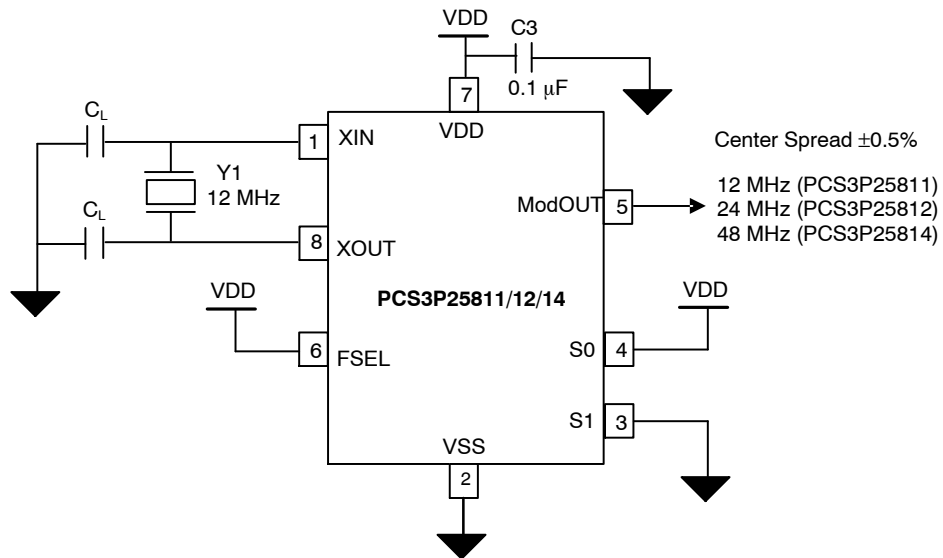
# PCS3P25811, PCS3P25812, PCS3P25814

**Table 7. AC ELECTRICAL CHARACTERISTICS**

Symbol	Parameter			Min	Typ	Max	Units
T <sub>JC</sub> (Note 2)	Cy–Cy Jitter, for ModOUT with Spread ON  (for Commercial temperature)	PCS3P25811	4 MHz			600	pS
			8 MHz			450	
		PCS3P25812	16 MHz			400	
			32 MHz			380	
		PCS3P25814	64 MHz			380	
			128 MHz			380	
	Cy–Cy Jitter, for ModOUT with Spread ON  (for Industrial temperature)	PCS3P25811	CLKIN = 6 MHz			500	pS
		PCS3P25812	CLKIN = 12 MHz			400	
		PCS3P25814	CLKIN = 24 MHz			380	
t <sub>ON</sub> (Note 2)	PLL Lock Time (Stable power supply, valid input clock to valid Clock on ModOUT)	Commercial Temperature				2	mS
		Industrial Temperature				3	

- Parameters are specified with 15 pF loaded outputs.
- Parameter is guaranteed by design and characterization. Not 100% tested in production.

## Application Schematic

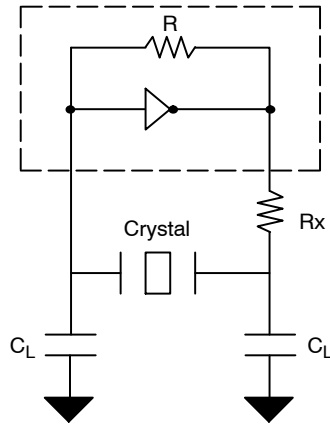


**Figure 2. Application Schematic**

**Table 8. TYPICAL CRYSTAL SPECIFICATIONS**

Fundamental AT Cut Parallel Resonant Crystal	
Nominal frequency	12 MHz
Frequency tolerance	±30 ppm or better at 25°C
Operating temperature range	–25°C to +85°C
Storage temperature	–40°C to +85°C
Load capacitance	18 pF
Shunt capacitance	7 pF maximum
ESR	25 Ω

NOTE: C<sub>L</sub> is Load Capacitance and Rx is used to prevent oscillations at overtone frequency of the Fundamental frequency.

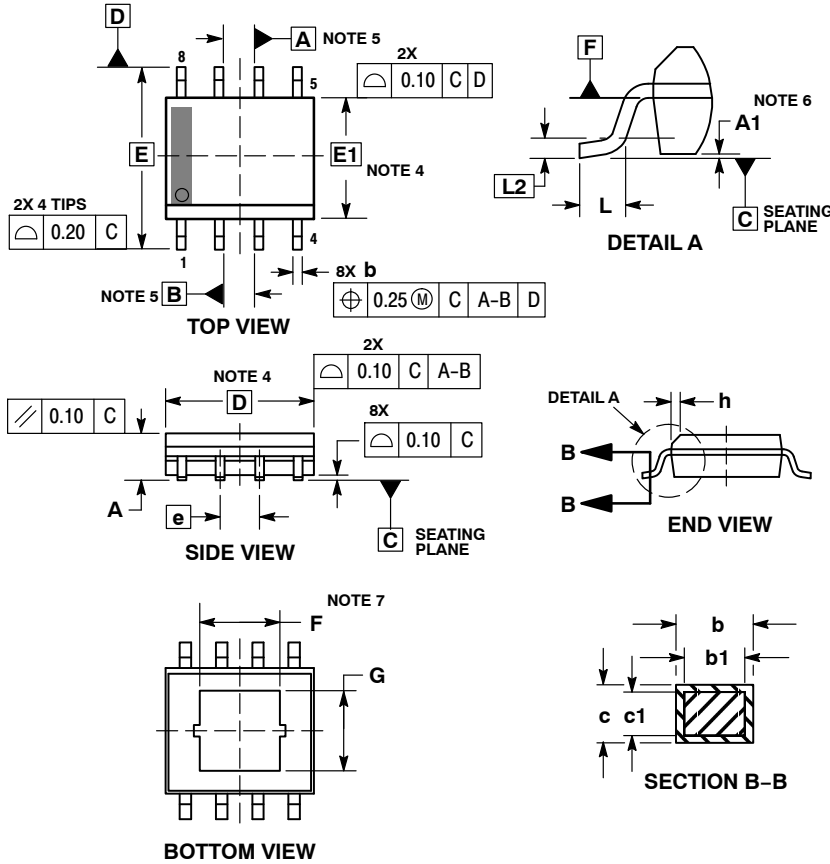


$C_L = 2 * (C_P - C_S)$ ,  
Where  $C_P$  = Load capacitance of crystal.  
 $C_S$  = Stray capacitance due to  $C_{IN}$ , PCB, Trace, etc.

**Figure 3. Typical Crystal Interface Circuit**

PACKAGE DIMENSIONS

SOIC8-NB EP  
CASE 751BU  
ISSUE B

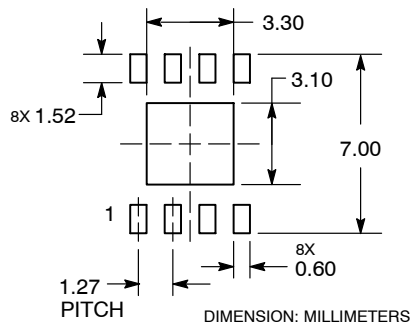


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.10mm IN EXCESS OF MAXIMUM MATERIAL CONDITION.
4. DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15mm PER SIDE. DIMENSION E DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25mm PER SIDE. DIMENSIONS D AND E ARE DETERMINED AT DATUM F.
5. DIMENSIONS A AND B ARE TO BE DETERMINED AT DATUM F.
6. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
7. TAB CONTOUR MAY VARY MINIMALLY TO INCLUDE TOOLING FEATURES.

MILLIMETERS		
DIM	MIN	MAX
A	1.35	1.75
A1	---	0.10
b	0.31	0.51
b1	0.28	0.48
c	0.17	0.25
c1	0.17	0.23
D	4.90 BSC	
E	6.00 BSC	
E1	3.90 BSC	
e	1.27 BSC	
F	1.55	3.07
G	1.55	3.07
h	0.25	0.50
L	0.40	1.27
L2	0.25 BSC	

RECOMMENDED  
SOLDERING FOOTPRINT\*

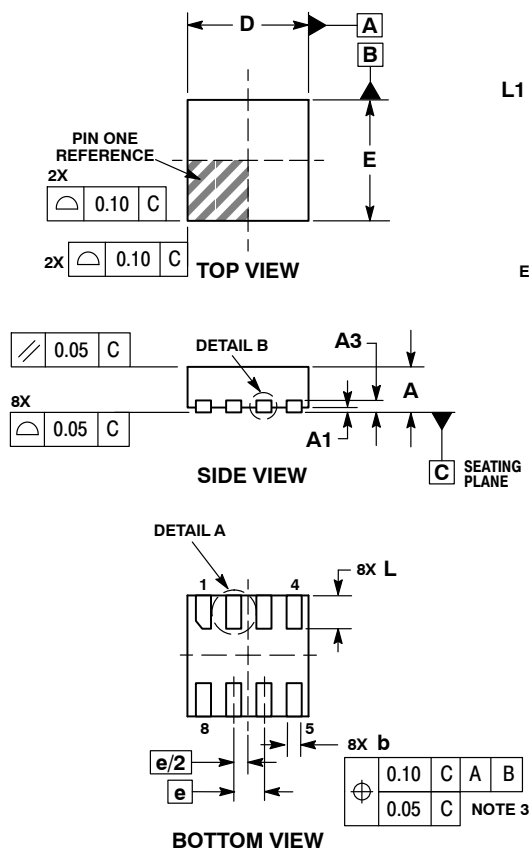


\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# PCS3P25811, PCS3P25812, PCS3P25814

## PACKAGE DIMENSIONS

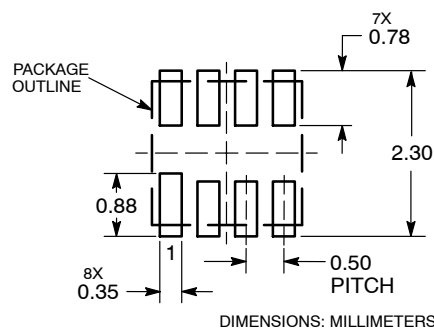
WDFN8 2x2, 0.5P  
CASE 511AQ  
ISSUE A



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM TERMINAL.

DIM	MILLIMETERS	
	MIN	MAX
A	0.70	0.80
A1	0.00	0.05
A3	0.20	REF
b	0.20	0.30
D	2.00	BSC
E	2.00	BSC
e	0.50	BSC
L	0.50	0.60
L1	---	0.15

## RECOMMENDED SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.




# PCS3P25811, PCS3P25812, PCS3P25814

**Table 9. ORDERING INFORMATION**

Part Number	Marking	Package Type	Temperature
PCS3P25811AG08SR	CGL	8-pin SOIC – Tape & Reel, Green	0°C to +70°C
P3P25812AG-08SR	CIL	8-pin SOIC – Tape & Reel, Green	0°C to +70°C
P3P25814AG-08SR	CKL	8-pin SOIC – Tape & Reel, Green	0°C to +70°C
P3P25811AG-08CR	CG	8L-WDFN (2 mm x 2 mm) – Tape & Reel, Green	0°C to +70°C
P3P25812AG-08CR	CI	8L-WDFN (2 mm x 2 mm) – Tape & Reel, Green	0°C to +70°C
P3P25814AG-08CR	CK	8L-WDFN (2 mm x 2 mm) – Tape & Reel, Green	0°C to +70°C

NOTE: A “microdot” placed at the end of last row of marking or just below the last row toward the center of package indicates Pb-free

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